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Date

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

: Vishnu K. Agarwal

Attorney Docket No.: 501082.16 (98-0616.15)

Serial No.

: 09/652.580

Group Art Unit

: 2825

Filed

: August 31, 2000

Examiner

: Caridad M. Everhart

Title

: DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A

CONDUCTIVE LAYER IN SAID DEVICE

Box Non-Fee Amendment Commissioner of Patents Washington, DC 20231

## **AMENDMENT**

Sir:

Please amend the above-captioned patent application as follows:

## In the Specification:

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

--Still other gases include diborane (B<sub>2</sub>H<sub>6</sub>); phosphine (PH<sub>3</sub>); and carbon-silicon compounds such as methylsilane (CH<sub>3</sub>SiH<sub>3</sub>) and hexamethyldisilane (CH<sub>3</sub>)<sub>3</sub>Si-Si(CH<sub>3</sub>)<sub>3</sub>; and hexamethyldisilazane (HMDS). Additional alternate embodiments of the current invention use hydrazine (N<sub>2</sub>H<sub>4</sub>), monomethylhydrazine, carbon tetrafluoride (CF<sub>4</sub>), CHF<sub>3</sub>, HCl, and boron trichloride (BCl<sub>3</sub>), which are also useful in passivating dielectrics, as addressed in copending application 09/114,847, now issued as U.S. Patent No. 6,201,276 B1. Also included are mixtures of any of the gases or types of gases described above. Exemplary non-plasma process parameters using these other gases include a flow rate of about 2 sccm to about 400 sccm for